



## Product Change Notification / NTDO-29LFMY057

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### Date:

22-Dec-2021

### Product Category:

Switching Regulators

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4680 Final Notice: Qualification of MaxPower Semiconductor (MAPW) as a new fabrication site for Die #3 of selected Micrel MIC2405x, and SPN030055 device families available in 28L VQFN (5x6x0.9mm) package using palladium coated copper with gold flash (CuPdAu) wire material.

### Affected CPNs:

[NTDO-29LFMY057\\_Affected\\_CPN\\_12222021.pdf](#)

[NTDO-29LFMY057\\_Affected\\_CPN\\_12222021.csv](#)

### Notification Text:

**PCN Status:** Final notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of MaxPower Semiconductor (MAPW) as a new fabrication site for Die #3 of selected Micrel MIC2405x, and SPN030055 device families available in 28L VQFN (5x6x0.9mm) package using palladium coated copper with gold flash (CuPdAu) wire material.

### Pre and Post Change Summary:

	Pre Change	Post Change

<b>Fabrication Location</b>	<b>Die # 1</b>	Microchip Technology Colorado (MCSO)	Microchip Technology Colorado (MCSO)
	<b>Die # 2</b>	M-MOS Semiconductor HK Taiwan Branch (MMOS) - Manufactured by Xfab	M-MOS Semiconductor HK Taiwan Branch (MMOS) - Manufactured by Xfab
	<b>Die # 3</b>	Analog Power Inc. (ANPI)	MaxPower Semiconductor (MAPW)
<b>Wafer Size</b>	<b>Die # 1</b>	6 inches	6 inches
	<b>Die # 2</b>	8 inches	8 inches
	<b>Die # 3</b>	8 inches	8 inches
<b>Assembly Site</b>		Unisem (M) Berhad Perak, Malaysia (UNIS)	Unisem (M) Berhad Perak, Malaysia (UNIS)
<b>Wire material</b>		CuPdAu wire	CuPdAu wire
<b>Die attach material</b>		84-1 LMISR4	84-1 LMISR4
<b>Molding compound material</b>		G770HCD	G770HCD
<b>Lead frame material</b>		A194	A194

**Impacts to Data Sheet:** None

**Change Impact:**None

**Reason for Change:**

To improve productivity by qualifying MaxPower Semiconductor (MAPW) as a new fabrication site for die# 3.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**January 10, 2022 (date code: 2203)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	September 2021					->	December 2021					January 2022				
Workweek	36	37	38	39	40		49	50	51	52	53	01	02	03	04	05
Qual Report Availability										X						
Final PCN Issue Date		X														
Estimated Implementation Date														X		

**Method to Identify Change:** Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**September 08, 2021: Issued final notification.

December 22, 2021: Re-issued final notification. Attached the Qualification Report and updated time table summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_NTDO-29LFMY057\\_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MIC24055YJL-TR

MIC24056YJL-TR

SPN030055-TR